



Tannlin Multilevel Stencils

The new Tannlin Multilevel stencil

Manufactured using the Tannlin proprietary laser process allows greater flexibility and control in the print process over standard SMT stencils.

Why use Tannlin Multilevel technology?

- To facilitate an increase or decrease of paste volume and deposit height on selected PCB areas where you have mixed component technology, large ground pads, intrusive reflow or coplanarity issues.
- To improve the stencil to board gasket and print repeatability where you have topography issues on PCBs e.g. labels, solder mask inconsistencies and tented vias.
- To allow simultaneous printing of 3D cavities on a PCB.

Specification

Step areas	20 - 200 microns with support for complex shapes
Step Ramp	controlled step ramp in 50 micron increments, optional matched squeegee blades
Positional accuracy	< 10 microns on the step areas
Material thickness	+/- 2% (primary steel and step steel)
Board side distortion	flat with no impact
Environmentally friendly	no hazardous chemicals or pollutants in process
Process	to be available at all Tannlin manufacturing facilities
Lead-time	half day quick turn service available

